

IN THE CLAIMS

Please amend the claims as follows:

Claims 1-7 (Canceled):

Claim 8 (Currently Amended): A manufacturing method of a head gimbal assembly with a thin-film magnetic head provided with a magnetoresistive effect element comprising the steps of:

forming a plurality of magnetoresistive effect elements on a wafer;

forming a plurality of pairs of connection pads, each pair of connection pads being electrically connected across each magnetoresistive effect element;

forming a plurality of thin-film short-circuit patterns on a surface of said wafer, each short-circuit electrically short-circuiting between each pair of connection pads; [[and]]

cutting said wafer into a plurality of bar members so that the plurality of magnetoresistive effect elements are aligned on each bar member;

cutting and separating each bar member into a plurality of individual magnetic head sliders;

assembling each individual magnetic head slider with a support member to form the head gimbal assembly; and

thereafter breaking each short-circuit pattern by laser radiation during a ~~predetermined manufacturing process of the magnetic head~~ subsequent manufacturing process of the magnetic head.

Claims 9-11 (Canceled).

Claim 12 (Original): The manufacturing method as claimed in claim 8, wherein each short-circuit pattern has a strip shape linearly connecting each pair of connection pads.

Claim 13 (Original): The manufacturing method as claimed in claim 8, wherein the short-circuit pattern forming step includes sputtering or depositing a good conductor layer, and etching the good conductor layer.

Claim 14 (Original): The manufacturing method as claimed in claim 13, wherein said good conductor layer is a gold, aluminum or platinum layer.

Claim 15 (Original): The manufacturing method as claimed in claim 8, wherein each short-circuit pattern has a thickness of 0.1-10 μm .